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Docket No.: M4065.0361/P361
(PATENT)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:
Whonchee Lee, et al.

Application No.: 09/653,411

Group Art Unit: 2815

Filed: August 31, 2000

Examiner: Joseph H. Nguyen

For: ELECTRO-MECHANICAL POLISHING
OF PLATINUM CONTAINER
STRUCTURE

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT (IDS)

U.S. Patent and Trademark Office
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Customer Window
Crystal Plaza Two, Lobby, Room 1B03
Arlington, VA 22202

Dear Sir:

Pursuant to 37 CFR 1.56, the attention of the Patent and Trademark Office is hereby directed to the references listed on the attached PTO/SB/08. It is respectfully requested that the information be expressly considered during the prosecution of this application, and that the references be made of record therein and appear among the "References Cited" on any patent to issue therefrom.

This Supplemental Information Disclosure Statement is filed before the mailing date of a first Office Action on the merits as far as is known to the undersigned.

A copy of each reference on PTO/SB/08 is attached.

A concise explanation of relevance of the items listed on form PTO/SB/08 is:

[x] not given

☐ given for each listed item

☐ given for only non-English language listed items

☐ in the form of an English language copy of a Search Report from a foreign patent office, issued in a counterpart application, which refers to the relevant portions of the references

The Examiner's attention is also directed to U.S. Application No.: 09/651,779, filed August 30, 2000, U.S. Application No.: 10/090,869, filed March 4, 2002, U.S. Application No.: 10/230,463, filed August 29, 2002, U.S. Application No.: 10/230,628, filed August 29, 2002, U.S. Application No.: 10/230,602, filed August 29, 2002, U.S. Application No.: 09/653,392, filed August 31, 2000, and U.S. Application No.: 09/651,808, filed August 30, 2000.

This Supplemental Information Disclosure Statement is not intended to constitute an admission that any patent, publication or other information referred to therein is "prior art" unless specifically designated as such.

In accordance with 37 CFR 1.97(g), the filing of this Supplemental Information Disclosure Statement shall not be construed to mean that a search has been made. It is submitted that the Supplemental Information Disclosure Statement is in compliance with 37 CFR 1.98 and the Examiner is respectfully requested to consider the listed references.

The Director is hereby authorized to charge any deficiency in the fees filed, asserted to be filed or which should have been filed herewith (or with any paper hereafter filed in this application by this firm) to our Deposit Account No. 04-1073, under Order No. M4065.0361/P361. A duplicate copy of this paper is enclosed.

Dated: November 20, 2003

Respectfully submitted,

By 

Thomas J. D'Amico

Registration No.: 28,371

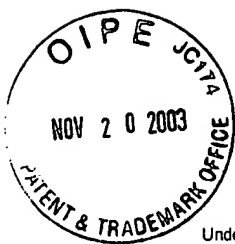
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PTO/SB/08A (10-01)

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Substitute for form 1449A/PTO INFORMATION DISCLOSURE STATEMENT BY APPLICANT <i>(use as many sheets as necessary)</i>				Complete if Known	
				Application Number	09/653,411
				Filing Date	August 31, 2000
				First Named Inventor	Whonchee Lee
				Art Unit	2815
				Examiner Name	Joseph H. Nguyen
Sheet	1	of	3	Attorney Docket Number	M4065.0361/P361

U.S. PATENT DOCUMENTS					
Examiner Initials*	Cite No. ¹	Document Number	Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear
		Number-Kind Code ² (if known)			
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	AB	2002/0025759	02-28-2002	Lee et al.	
	AC	2002/0025760	02-28-2002	Lee et al.	
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INFORMATION DISCLOSURE STATEMENT BY APPLICANT <i>(use as many sheets as necessary)</i>				Application Number	09/653,411
				Filing Date	August 31, 2000
				First Named Inventor	Whonchee Lee
				Art Unit	2815
				Examiner Name	Joseph H. Nguyen
Sheet	2	of	3	Attorney Docket Number	M4065.0361/P361

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Examiner Initials*	Cite No. ¹	Foreign Patent Document	Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear	T ⁶
		Country Code ³ -Number ⁴ -Kind Code ⁵ (if known)				
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¹ Applicant's unique citation designation number (optional). ² See attached Kinds Codes of USPTO Patent Documents at www.uspto.gov or MPEP 901.04. ³ Enter Office that issued the document, by the two-letter code (WIPO Standard ST.3). ⁴ For Japanese patent documents, the indication of the year of the reign of the Emperor must precede the application number of the patent document. ⁵ Kind of document by the appropriate symbols as indicated on the document under WIPO Standard ST. 16 if possible. ⁶ Applicant is to place a check mark here if English language Translation is attached.

NON PATENT LITERATURE DOCUMENTS			
Examiner Initials*	Cite No. ¹	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T ²
	CA	KONDO, S. et al., "Abrasive-Free Polishing for Copper Damascene Interconnection," Journal of the Electrochemical Society, Vol. 147, No. 10, pp. 3907-3913, (2000)	
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				Filing Date	August 31, 2000
				First Named Inventor	Whonchee Lee
				Group Art Unit	2815
				Examiner Name	Joseph H. Nguyen
Sheet	3	of	3	Attorney Docket Number	M4065.0361/P361

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CF	McGraw-Hill, "Chemical bonding," Concise Encyclopedia of Science & Technology, Fourth Edition, Sybil P. Parker, Editor in Chief, p. 367, McGraw-Hill, New York, New York, 1998.	
CG	PhysicsWorld. Hard Materials (excerpt of Superhard superlattices) [online]. S. Barnett and A. Madan, Physics World, January 1998, Institute of Physics Publishing Ltd., Bristol, United Kingdom. Retrieved from the Internet on July 29, 2002. <URL: http://physicsweb.org/box/world/11/1/11/world-11-1-11-1 >.	
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CI	ATMI, Inc., adapted from a presentation at the Semicon West '99 Low Dielectric Materials Technology Conference, San Francisco, California, July 12, 1999, pp. 13-25.	
CJ	Micro Photonics, Inc. CSM Application Bulletin. Low-load Micro Scratch Tester (MST) for characterisation of thin polymer films [online]. 3 pages. Retrieved from the Internet on July 25, 2002. <URL: http://www.microphotonics.com/mstABpoly.html >.	
CK	Micro Photonics, Inc. CSM Nano Hardness Tester [online]. 6 pages. Retrieved from the Internet on July 29, 2002. <URL: http://www.microphotonics.com/nht.html >.	

Examiner Signature		Date Considered	
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*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

¹Applicant's unique citation designation number (optional). ²Applicant is to place a check mark here if English language Translation is attached.